PCN Number: 20180221003	PCN Date:	Febru	uary 22, 2018		
Title: Datasheet for OPA211, OPA2211					
Customer Contact: PCN Manager		De	pt: Quality Servi	ces	
Change Type:			1		
	sign		Wafer Bump Site		
	ta Sheet		Wafer Bump Materia		
	t number change		Wafer Bump Process	<u>S</u>	
	st Site		Wafer Fab Site		
Packing/Shipping/Labeling Tes	st Process	$\dashv \vdash$	Wafer Fab Materials Wafer Fab Process		
Notif	ication Details		Water Fab Process		
	ication Details				
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.					
TEXAS INSTRUMENTS			OPA211, OPA		
	SBC)S377J-O	CTOBER 2006-REVISED FEBRUAR	RY 2018	
Changes from Revision I (June 2016) to Revision J				Page	
Added "Medical Instrumentation" to Applications see	ction			1	
Changed product status from mixed product status	Changed product status from mixed product status to production data				
Deleted Device Comparison table				4	
	Added NC pin table notes to pin diagrams in the Pin Configurations and Functions section				
Changed typical input bias current value from ±60 nA to 60 nA in <i>Electrical Characteristics</i> : V _S = ±2.25 to ±18 V (OPAx211) table					
Changed maximum input bias current from ±175 nA to 175 nA in Electrical Characteristics: V _S = ±2.25 to ±18 V (OPAx211) table					
Changed OPA211 input bias current maximum value from ± 200 to 200 nA in <i>Electrical Characteristics</i> : $V_S = \pm 2.25$ to ± 18 V (OPAx211) table					
Changed input bias current typical value from ±50 nA to 50 nA in <i>Electrical Characteristics</i> : V _S = ±2.25 to ±18 V for High Grade OPA211 table					
 Changed input bias current maximum value from ±1 V for High-Grade OPA211 table 				11	
Changed maximum input bias current value from ±200 nA to 200 nA n <i>Electrical Characteristics</i> : V _S = ±2.25 to ±18 V for High-Grade OPA211 table					
Changed formatting of document reference in <i>EMI Rejection</i> section					
Changed formatting of document references in SON Layout Guidelines section				31	
Changed formatting of document references in Relation	nted Documentation section			32	
The datasheet number will be shanging					
The datasheet number will be changing. Device Family	Change From:		Change To:		
•			-		
OPA211, OPA2211	SBOS377I		SBOS377J		
These changes may be reviewed at the date	asheet links provide	d.			
http://www.ti.com/product/OPA211					
Reason for Change:					
To accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.					
Changes to product identification resulting from this PCN:					
None.	_				

Product Affected:			
OPA211AID	OPA211AIDR	OPA211ID	OPA211IDRGT
OPA211AIDG4	OPA211AIDRG4	OPA211IDGKR	OPA2211AIDDA
OPA211AIDGKR	OPA211AIDRGR	OPA211IDGKT	OPA2211AIDDAR
OPA211AIDGKT	OPA211AIDRGT	OPA211IDR	OPA2211AIDRGR
OPA211AIDGKTG4	OPA211AIDRGTG4	OPA211IDRGR	OPA2211AIDRGT

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
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Asia Pacific	PCNAsiaContact@list.ti.com
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